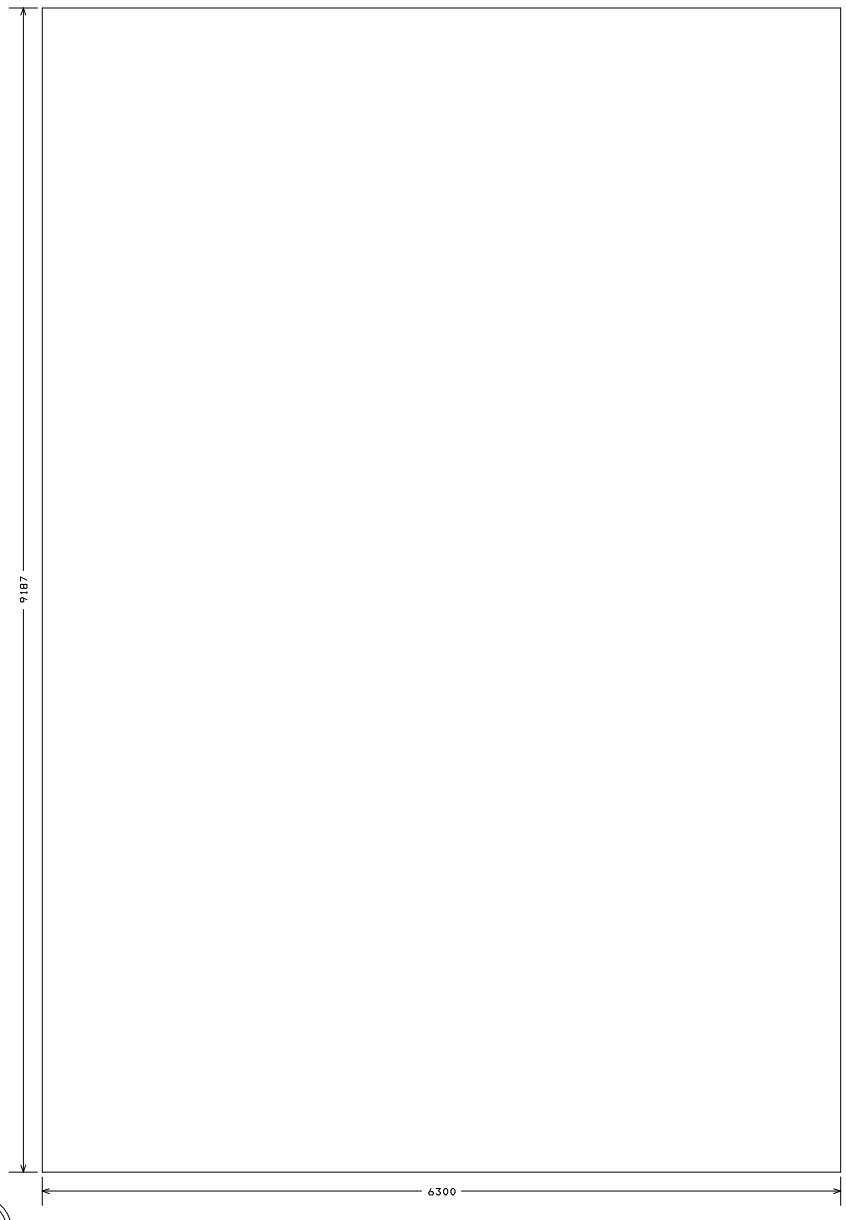
BPM TGF
Rev 2.0, Oct 12 2004

Fabrication Drawing



Layer Stackup:

1) Component Side
2) Ground Plane: Analog
3) Inner Layer1
4) Ground Plane: Digital
5) Inner Layer2
6) Power - VCC/1.5V
7) Power VDD
8) Inner Layer3
9) Ground Plane: Digital
10) Inner Layer4
11) Ground Plane: Digital
12) Solder Side

SMT Pad Count:

Top: 1927
Bottom: 452

Thru Hole Count: 2008

Job Spec's

Material: FR-4
Material Thickness: 0.063"
Copper Weight: 1/2oz Inner/Outer Layers
Finnish/Plating: Tin-Lead
SolderMask Type: LPI
SilkScreen Layers: Top & Bottom
Min. Trace Width: 5mil
Min. Trace Spacing: 5mil
Smallest Hole Size: 10mil
Largest Hole Size: 125mil
Job Turn Around Time: 10 Day Turn
Job Qnt.: 38 Pieces

Controled Impedence:

All Top Layer 9mil traces are to be 50ohms to Layer 2 GND Plane

All Bottom Layer 9mil traces are to be 50ohms to Layer 11 GND Plane